What is claimed is:

1. A method for making an organic electronic device comprising:

a. providing an adhesive-coated release liner from which a pattern has been cut,

b. applying the adhesive-coated side of the patterned release liner to an electrode substrate to form a composite structure having at least a portion of the electrode substrate exposed,

c. depositing one or more organic electronic elements on the exposed electrode of the composite structure,

d. removing the release liner from the composite structure, and

e. adhering a sealing layer to the exposed adhesive of the composite structure.

2. The method of claim 1 wherein a protective film is applied to the composite structure after the release liner is removed, which protective film is removed prior to adhering the sealing layer.

3. The method of claim 1 wherein the adhesive-coated liner is thicker in the z direction than the organic electronic elements.

4. The method of claim 1 wherein the adhesive is selected from the group comprising hot melt adhesives, pressure sensitive adhesives, curable adhesives, and filled adhesives.

5. The method of claim 4 wherein the filled adhesive is selected from the group comprising electrically conductive adhesives, thermally conductive adhesives, and desiccating adhesives.

6. The method of claim 5 wherein the filled adhesive is used in conjunction with an unfilled adhesive.

7. The method of claim 1 wherein the adhesive-coated liner is selected from the group comprising polypropylene films, metal foils coated with siloxanes or fluorocarbons, polyester coated with siloxanes or fluorocarbons, and fluoropolymer films.

8. The method of claim 1 wherein multiple adhesive-coated liners are applied to the electrode substrate and are removed at different stages during organic electronic element deposition.

9. The method of claim 1 wherein the sealing layer is a counter electrode.

10. The method of claim 9 wherein the material comprising the counter electrode is selected from the group comprising lithium fluoride, aluminum, barium, ytterbium, samarium, lithium, indium tin oxide, fluorine tin oxide, zinc oxide, calcium, magnesium, silver, gold, and alloys of calcium and magnesium.

11. The method of claim 1 wherein the sealing layer comprises a partial organic electronic device construction that is laminated to the composite structure.

12. The method of claim 1 wherein a counter electrode layer is applied on top of the final organic element layer and the sealing layer is a protective layer.

13. The method of claim 12 wherein the adhesive-coated liner is thicker in the z direction than the organic electronic elements and the counter electrode layer.

14. The method of claim 12 wherein the material comprising the protective layer is selected from the group comprising metallized polymer films, polymer multilayer films, metal plates, foils, and thin flexible glasses.

15. The method of claim 13 wherein the material comprising the counter electrode is selected from the group comprising calcium, aluminum, and indium tin oxide.

16. The method of claim 1 wherein the organic electronic device is an organic light emitting diode.

17. The method of claim 16 wherein the substrate is selected from the group comprising glass and polymer multilayer films, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises, and the cathode comprises lithium fluoride and aluminum.

18. A method for making an organic electronic device comprising:

a. coating an adhesive in a pre-determined pattern on an electrode substrate to form a composite structure wherein areas of the substrate remain exposed;

b. applying a mask or release liner to the patterned adhesive such that at least a portion of the exposed substrate areas remain exposed;

c. depositing one or more organic electronic elements on the composite structure;

d. removing the mask or release liner from the adhesive; and

e. applying a sealing layer.

19. The method of claim 18 wherein a protective film is applied to the composite structure after the release liner is removed, which protective film is removed prior to adhering of the sealing layer.

20. The method of claim 18 wherein the adhesive-coated liner is thicker in the z direction than the organic electronic elements.

21. The method of claim 18 wherein the adhesive is selected from the group comprising hot melt adhesives, pressure sensitive adhesives, curable adhesives, and filled adhesives.

22. The method of claim 21 wherein the filled adhesive is selected from the group comprising electrically conductive adhesives, thermally conductive adhesives, and desiccating adhesives.

23. The method of claim 22 wherein the filled adhesive is used in conjunction with an unfilled adhesive.

24. The method of claim 18 wherein the adhesive-coated liner is selected from the group comprising polypropylene films, metal foils coated with siloxanes or fluorocarbons, polyester coated with siloxanes or fluorocarbons, and fluoropolymer films.

25. The method of claim 18 wherein multiple adhesive-coated liners are applied to the electrode substrate and are removed at different stages during organic electronic element deposition.

26. The method of claim 18 wherein the adhesive is one or both of partially cured and dried between a. and b.

27. The method of claim 18 wherein the sealing layer is a counter electrode.

28. The method of claim 27 wherein the material comprising the counter electrode is selected from the group comprising lithium fluoride, calcium, aluminum, barium, ytterbium, samarium, lithium, and indium tin oxide, fluorine tin oxide, zinc oxide, calcium, magnesium, silver, gold, and alloys of calcium and magnesium.

29. The method of claim 18 wherein the sealing layer comprises a partial organic electronic device construction that is laminated to the composite structure.

30. The method of claim 18 wherein a counter electrode layer is applied after the final organic element layer and the sealing layer is a protective layer.

31. The method of claim 30 wherein the adhesive-coated liner is thicker in the z direction than the organic electronic elements and the counter electrode layer.

32. The method of claim 31 wherein the material comprising the protective layer is selected from the group comprising metallized polymer films, polymer multilayer films, metal plates, foils, and thin flexible glasses.

33. The method of claim 32 wherein the material comprising the counter electrode is selected from the group comprising lithium fluoride, calcium, aluminum, barium, ytterbium, samarium, lithium, indium tin oxide, fluorine tin oxide, zinc oxide, calcium, magnesium, silver, gold, and alloys of calcium and magnesium.

34. The method of claim 18 further comprising the step of fully curing the adhesive after the device has been constructed.

35. The method of claim 18 wherein the organic electronic device is an organic light emitting diode.

36. The method of claim 35 wherein the substrate is selected from glass and polymer multilayer films, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises, and the cathode comprises lithium fluoride and aluminum.

37. An article comprising an organic electronic device wherein the layers between the anode and cathode are surrounded by an adhesive layer and wherein the circumference of the adhesive layer is equal to the circumference of one or both of the electrode substrate or sealing layer.

38. The article of claim 37 wherein the adhesive is selected from the group comprising hot melt adhesives, pressure sensitive adhesives, curable adhesives, and filled adhesives.

39. The article of claim 38 wherein the filled adhesive is selected from the group comprising electrically conductive adhesives, thermally conductive adhesives, and dessicating adhesives.

40. The article of claim 37 wherein the circumference of the adhesive layer is greater than that of an electrode.

41. The article of claim 37 wherein the article is an organic light emitting diode.

42. The article of claim 37 wherein the substrate comprises glass the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises, and the cathode comprises lithium fluoride and aluminum.